



Advance Product Change Notification

201912021AW

Issue Date: 29-Mar-2020 **WITHDRAWAL**

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Management Summary

NXP is modifying the ASIC die thickness for the FXLS8962AFR1 and FXLS8965AFR1 products. Change is being withdrawn since qualification study did not demonstrate an improvement.

Change Category

☐ Wafer Fab Process	☒ Assembly Process	☐ Product Marking	☐ Test Location	☐ Design
☐ Wafer Fab Materials	☐ Assembly Materials	☐ Mechanical Specification	☐ Test Process	☐ Errata
☐ Wafer Fab Location	☐ Assembly Location	☐ Packing/Shipping/Labeling	☐ Test Equipment	☐ Electrical spec./Test coverage
☐ Firmware	☐ Other			

ASIC Die Thickness Increase for FXLS8962AFR1 and FXLS8965AFR1 Products

Description of Change

NXP Semiconductors announces an increase in the ASIC die thickness for the FXLS8962AFR1 and FXLS8965AFR1 products from 100 μm to 150 μm . The thickness increase will occur if a qualification study demonstrates that the change improves robustness to UHAST stress.

Reason for Change

Improved robustness to UHAST stress.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Not applicable

Production

Planned first shipment 30-Apr-2020

Withdrawal Information

NXP Semiconductors announces the withdrawal of the proposed change of an increase in the ASIC die thickness, from 100 μm to 150 μm , for the FXLS8962AFR1 and FXLS8965AFR1 products. The qualification study did NOT demonstrate improvement in robustness to UHAST stress, as expected.

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

The change will only be implemented if the qualification study demonstrates that the change improves robustness to UHAST stress.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

The Self Qualification Report will be ready on 12-Dec-2019.

The Final PCN is planned to be issued on: 31-Jan-2020.

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 28-Apr-2020.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Dan Sadler

Position Product Line Manager

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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NXP Semiconductors

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
FXLS8962AFR1	935345579115	FXLS8962AF	3axis 2/4/8/16g 2X2DFN10	SOT1615-3	VSON10	RFS	Sensors